

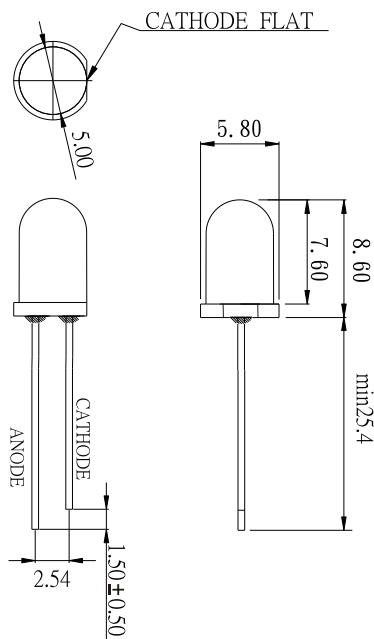
Device Selection Guide

Part Number EOL-	Luminous Intensity $I_v(\text{mcd}) @ I_F = 20 \text{ mA}$		Viewing Angle $2\theta_{1/2}$ $@ I_F = 20 \text{ mA}$	Dominant Wavelength $\lambda_d(\text{nm}) @ I_F = 20 \text{ mA}$	V_F $@ I_F = 20 \text{ mA}$		$I_R(\mu\text{A})$ $@ V_R = 5 \text{ V}$	Stand Off	Epoxy Color
	Min.	Typ.	Typ.	Typ.	Typ.	Max.	Max.		
5FGFCC0-DG	580	750	30°	570	2.0	2.4	10	No	Clear

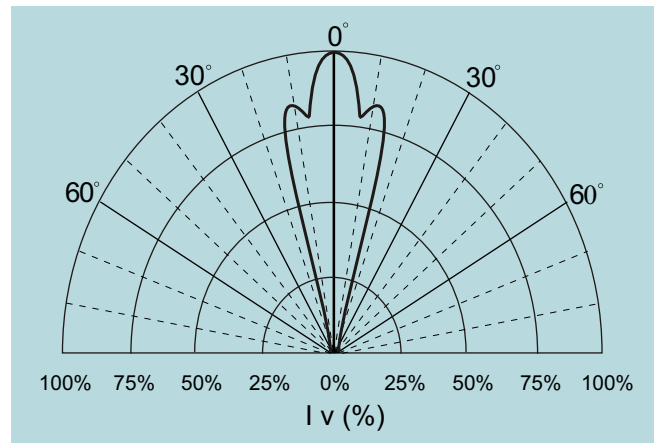
BIN#	Q	R*
Intensity(mcd) @ $I_F = 20 \text{ mA}$	580-810	810-1135

Notes: [1] Tolerance for Min. Value + 15%

Package Dimensions



Beam Pattern



Note:

- All dimensions are in millimeter (mm).
- Unspecified tolerance: $\pm 0.20\text{mm}$.
- Protruded resin 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to change without notice.

Absolute Maximum Ratings at $T = 25^\circ\text{C}$

Parameter	Symbol	
Peak Forward Current	I_{fm}	100mA
Average Forward Current	I_f	30mA
Reverse Voltage	V_r	5V
Operating Temperature Range	T_{opr}	-30°C to + 85°C
Storage Temperature Range	T_{sto}	-40°C to + 100°C
Lead Soldering Temperature	T_{sol}	260°C / 5 Secondes

Notes: Duty Ratio=1/10, Pulse Width=0.1 ms